

Fig. 1

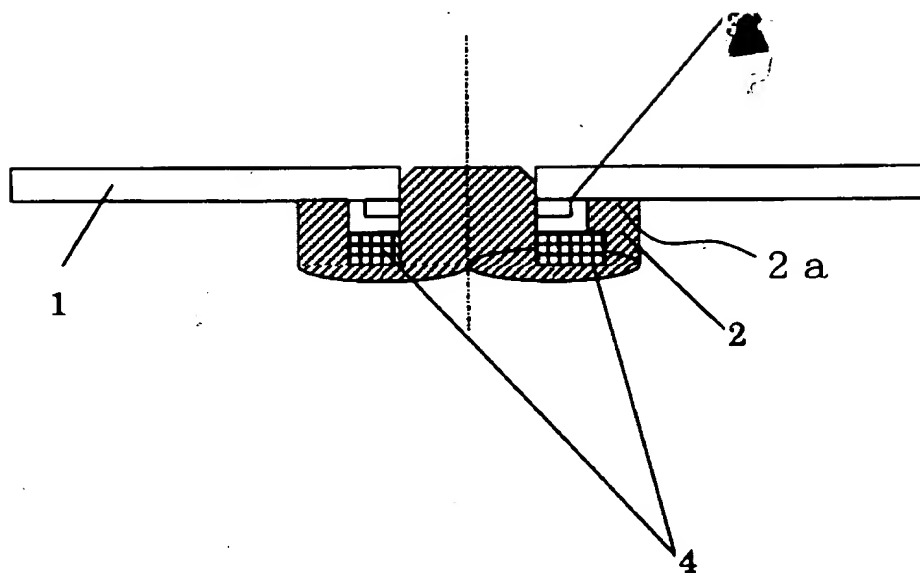


Fig. 2

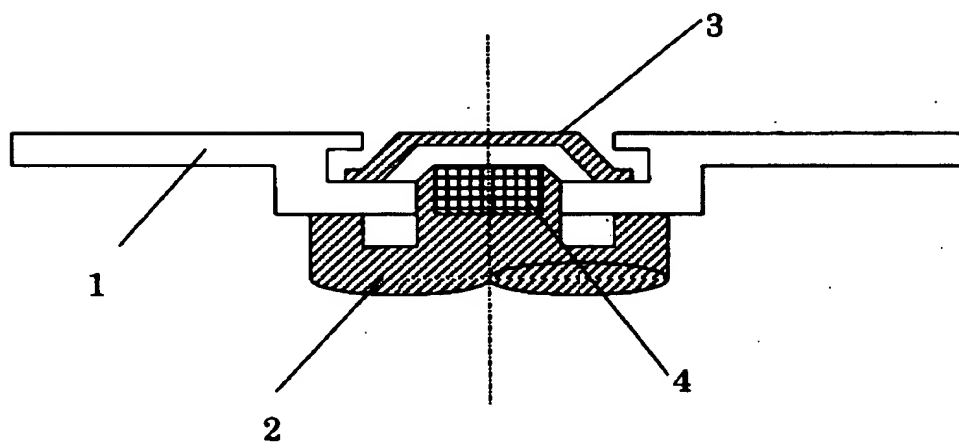


Fig. 3

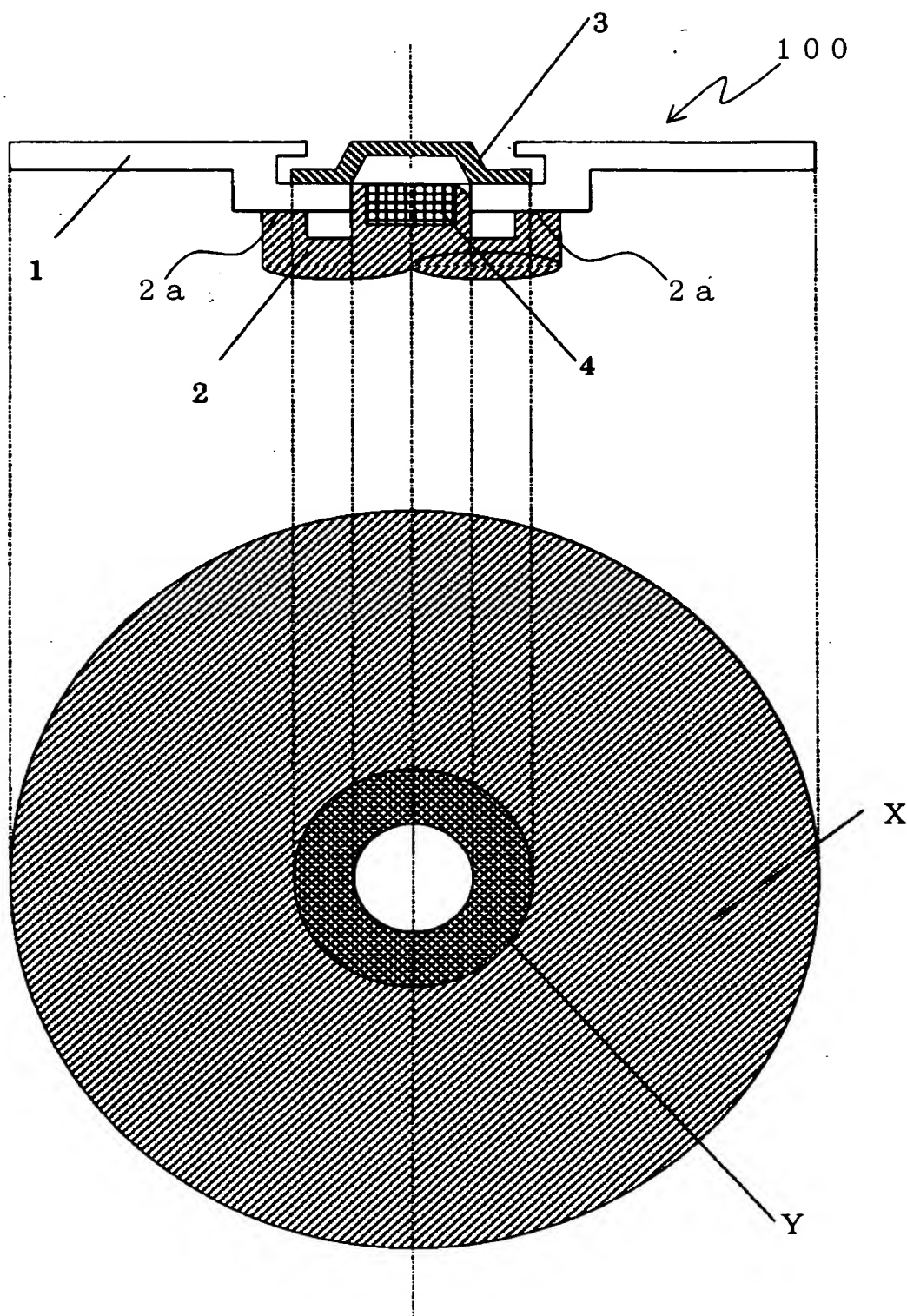


Fig. 4A

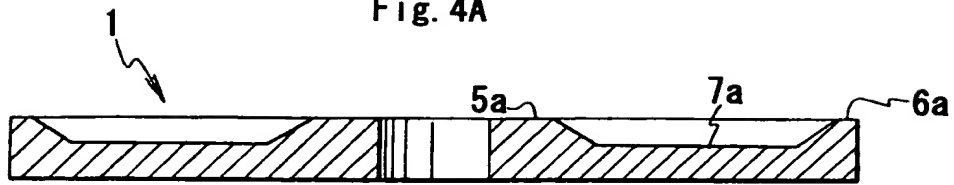


Fig. 4B

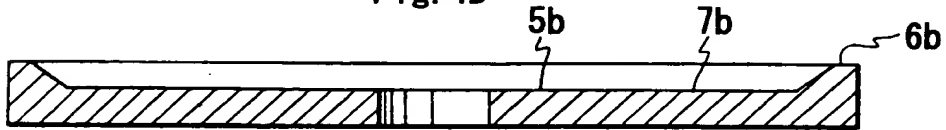


Fig. 4C

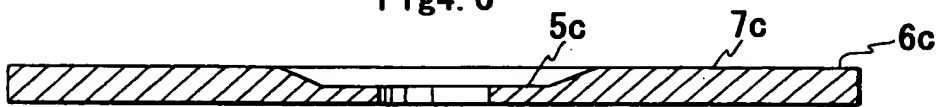


Fig. 4D

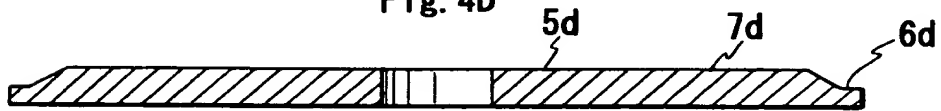


Fig. 4E

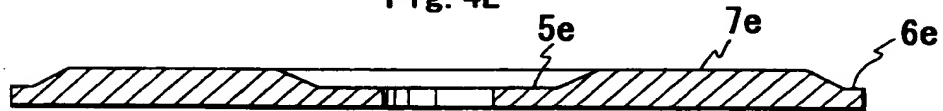


Fig. 4F

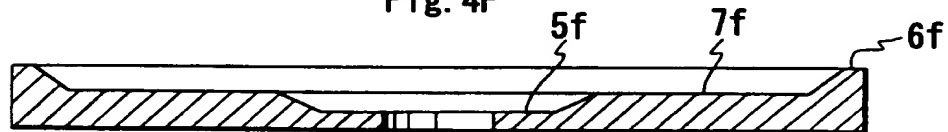


Fig. 4G

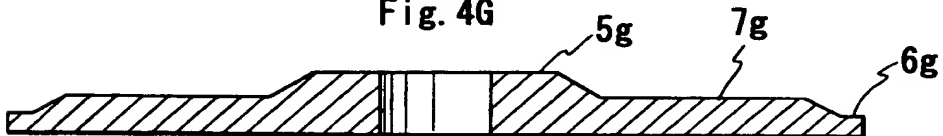


Fig. 4H

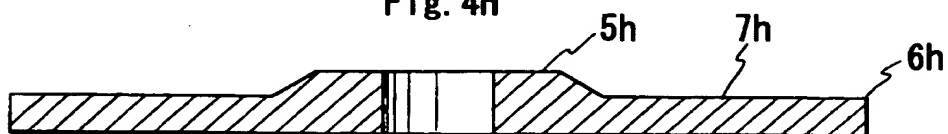


Fig. 4I

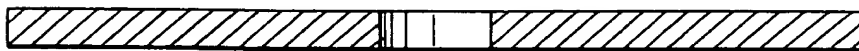


Fig. 5A

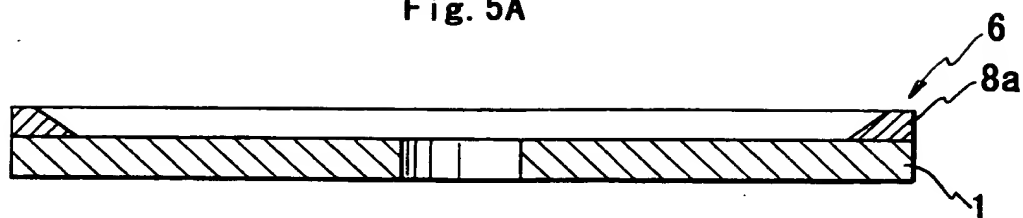


Fig. 5B



Fig. 5C

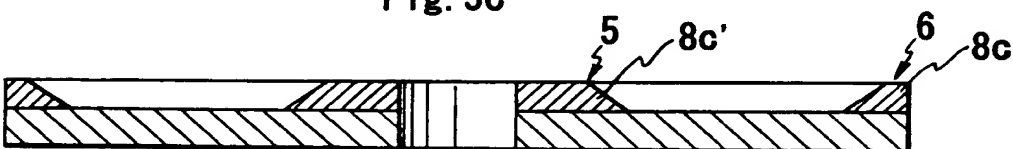


Fig. 5D

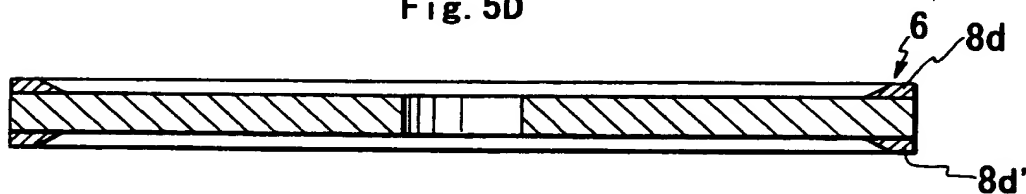


Fig. 5E

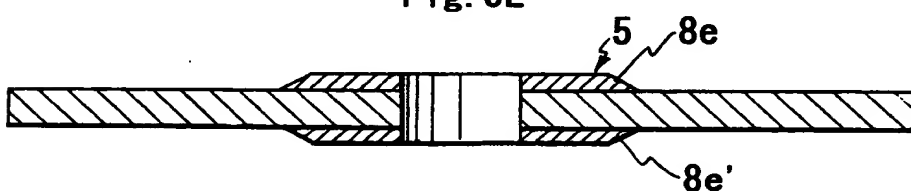


Fig. 5F

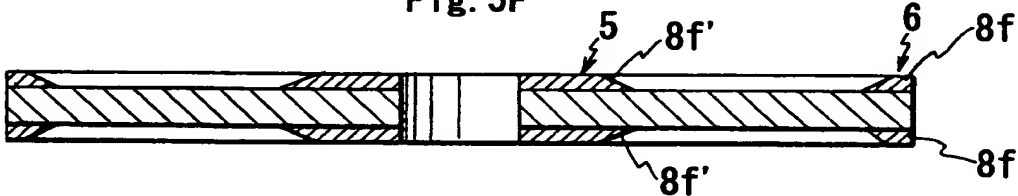


Fig. 5G

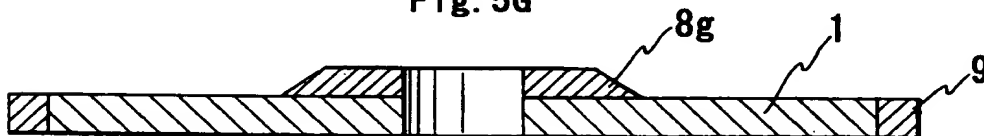


Fig. 6

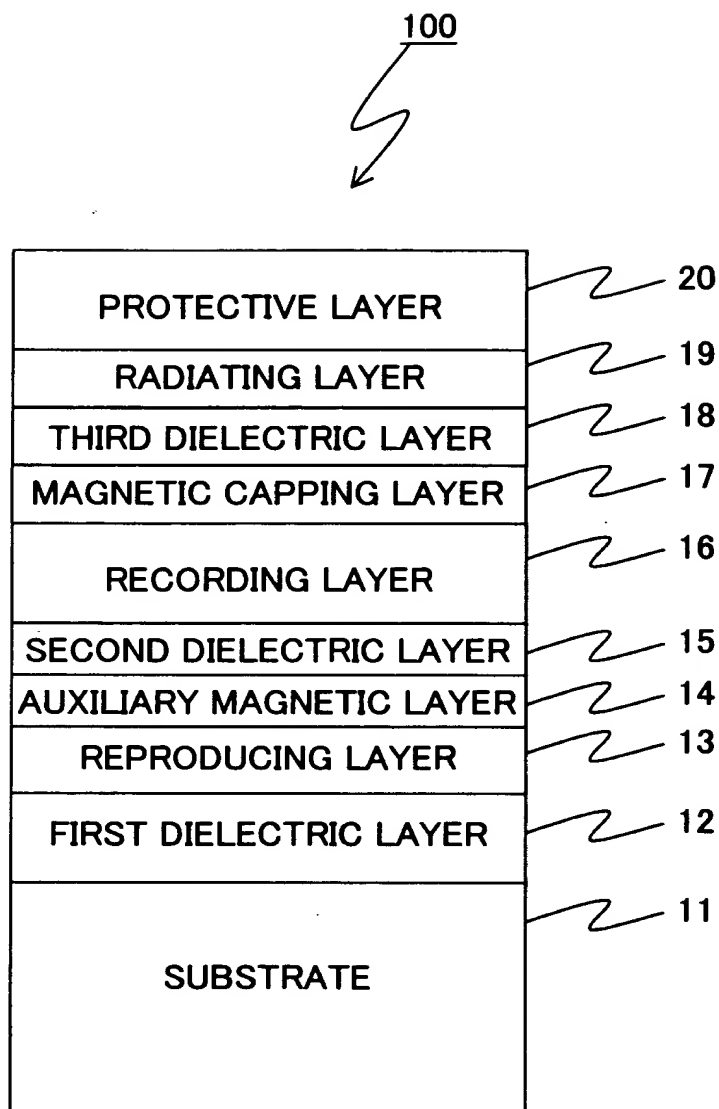


Fig. 7

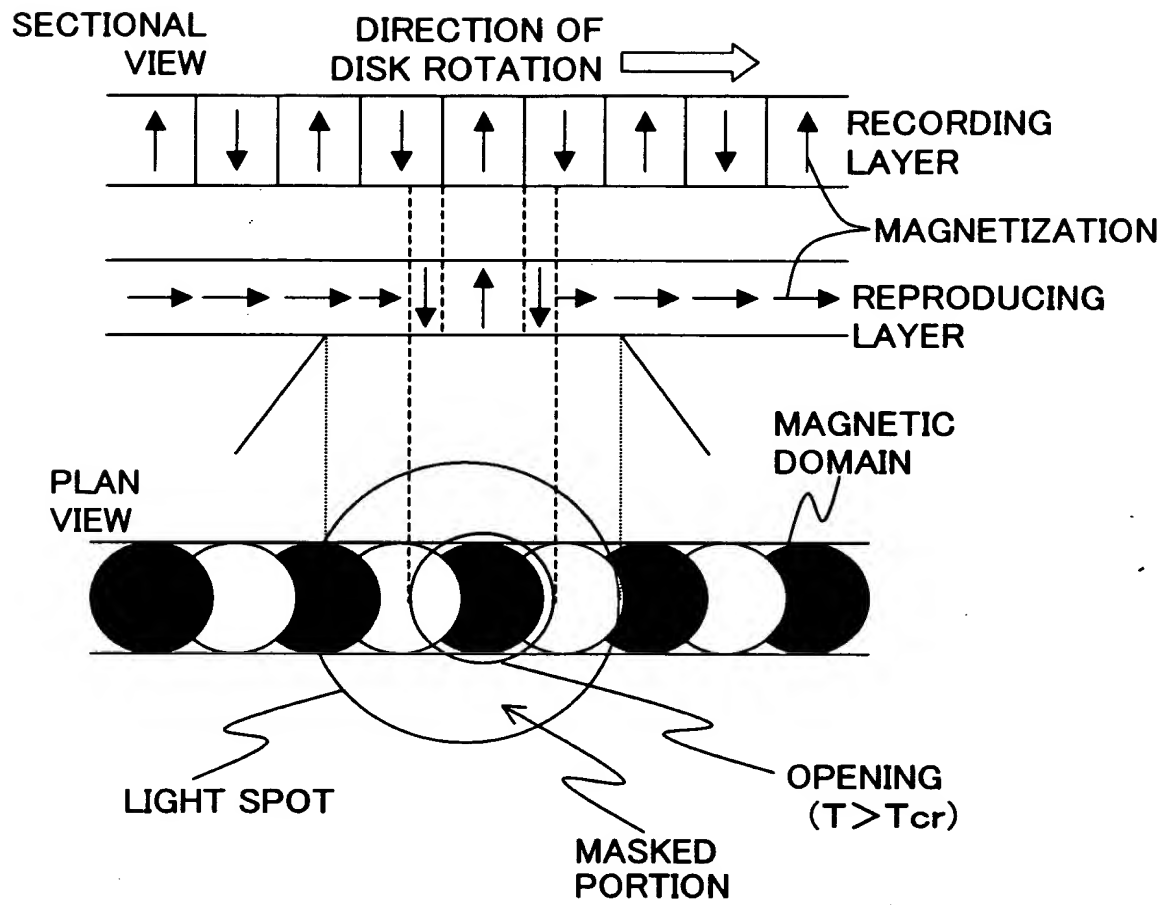


Figure 1 is a cross-sectional view of the device 100. The device 100 includes a substrate 22a, a layer 22b, and a central core 100. A dimension line 'd' indicates the thickness of the substrate 22a.

Fig. 9

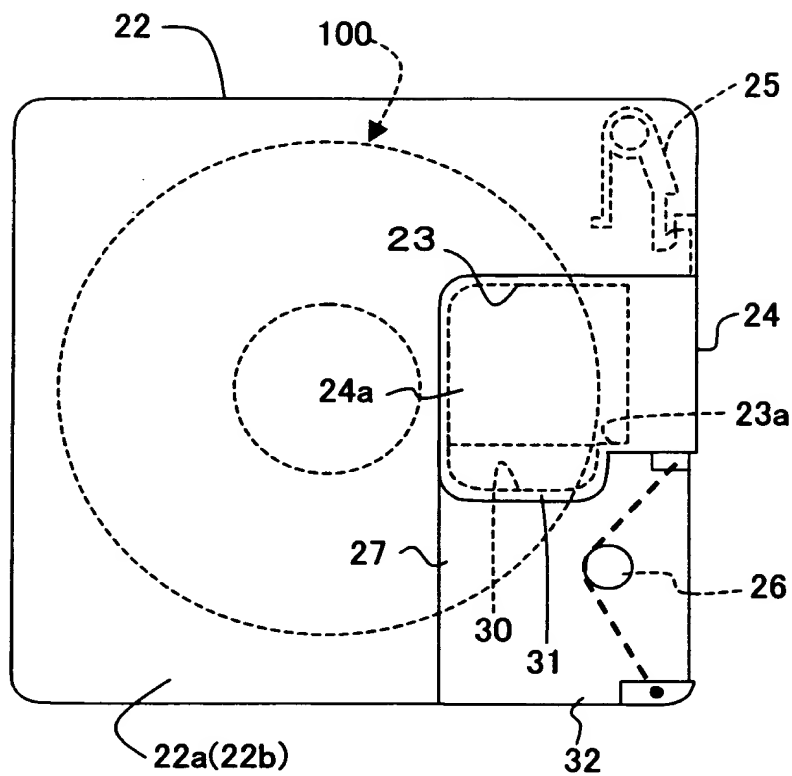




Fig. 10

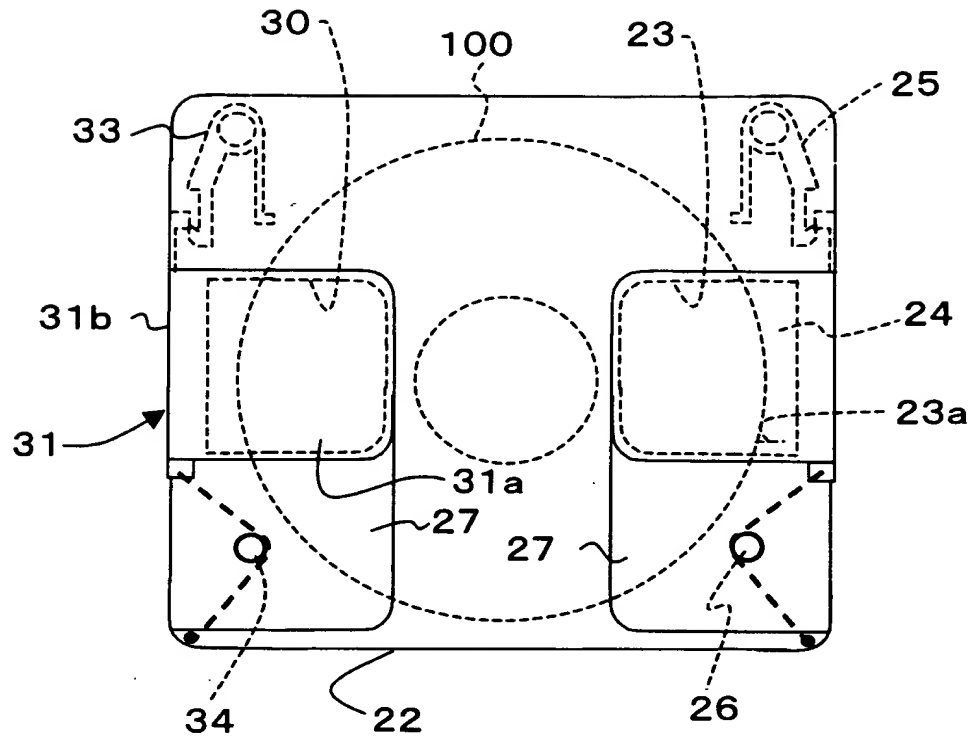


Fig. 11A

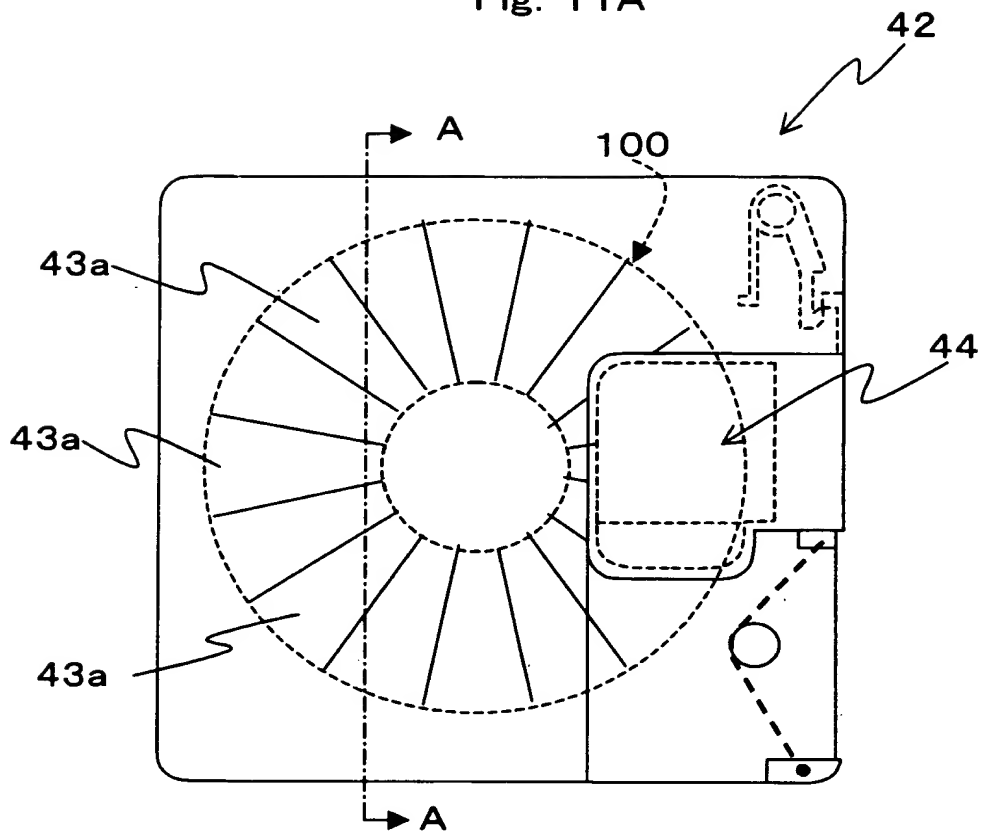


Fig. 11B

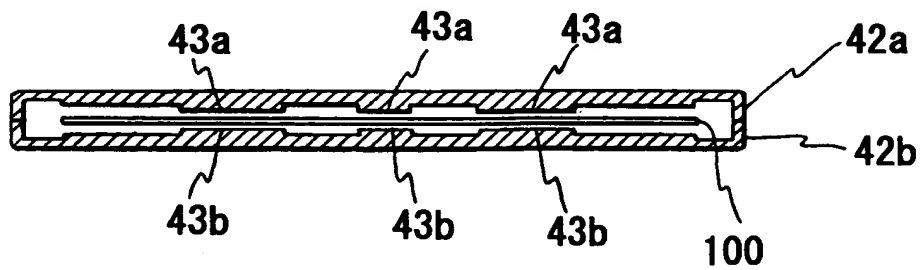


Fig. 12A

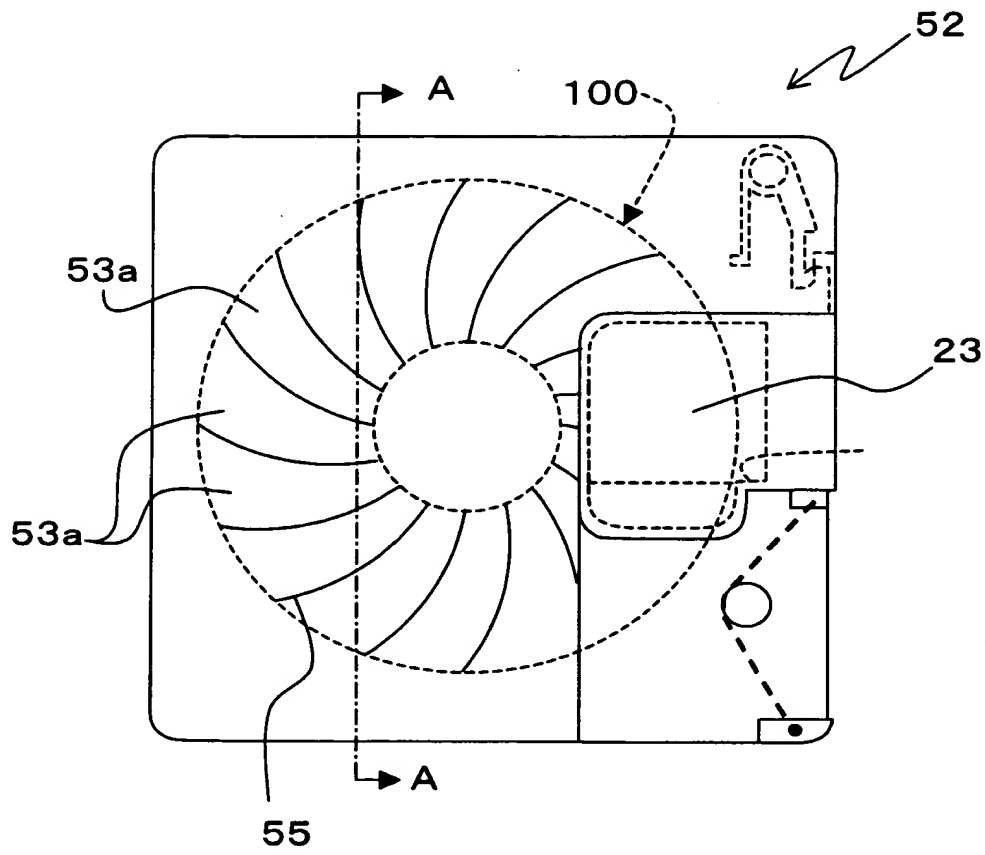


Fig12. B

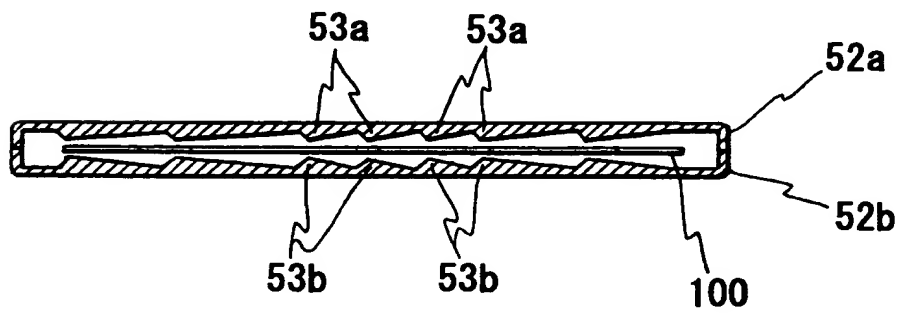


Fig. 13A

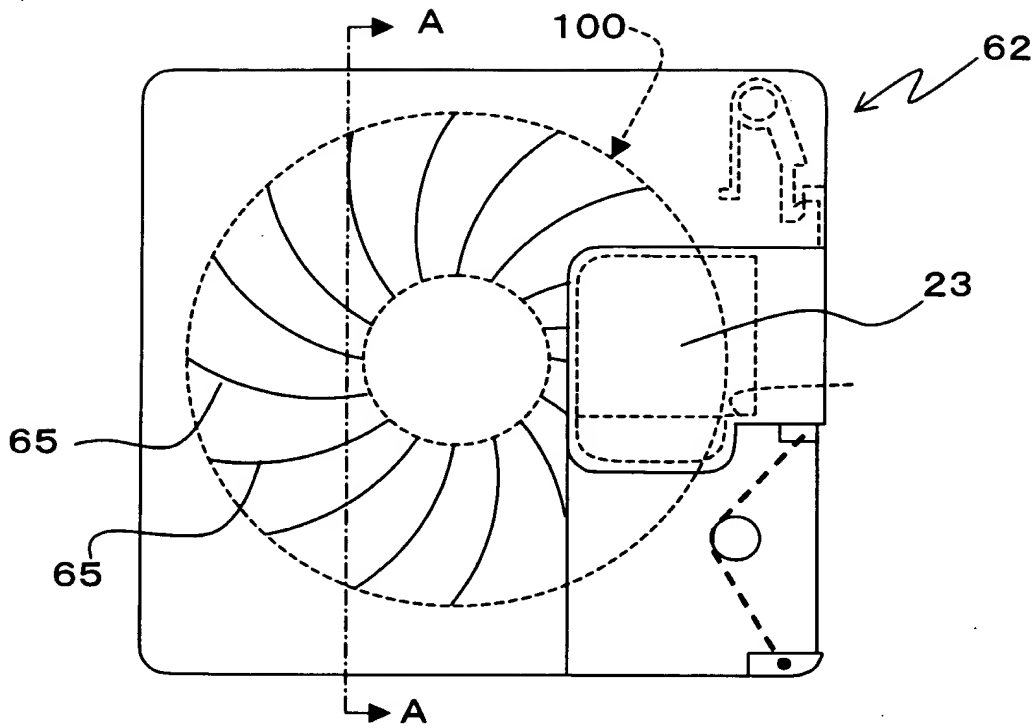


Fig. 13B

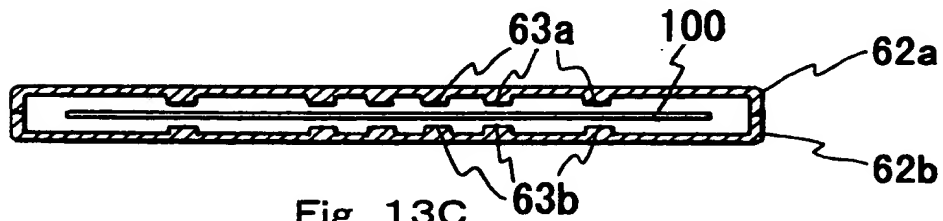


Fig. 13C

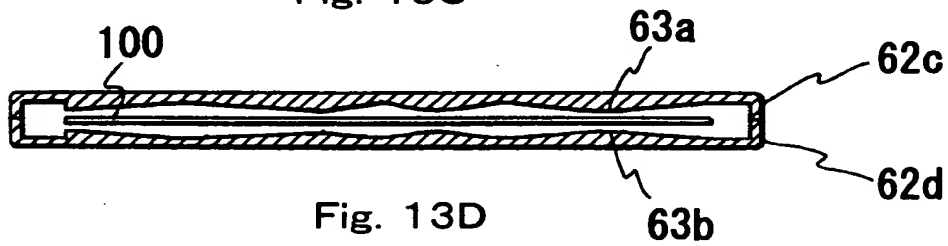


Fig. 13D

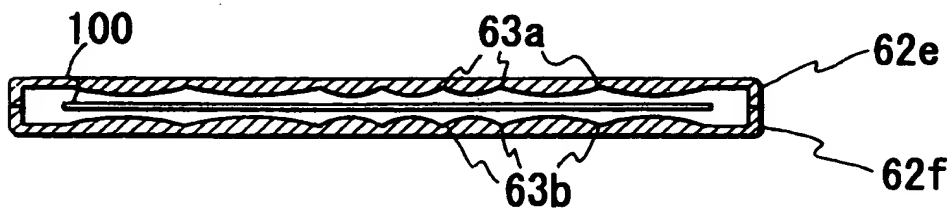


Fig. 14A

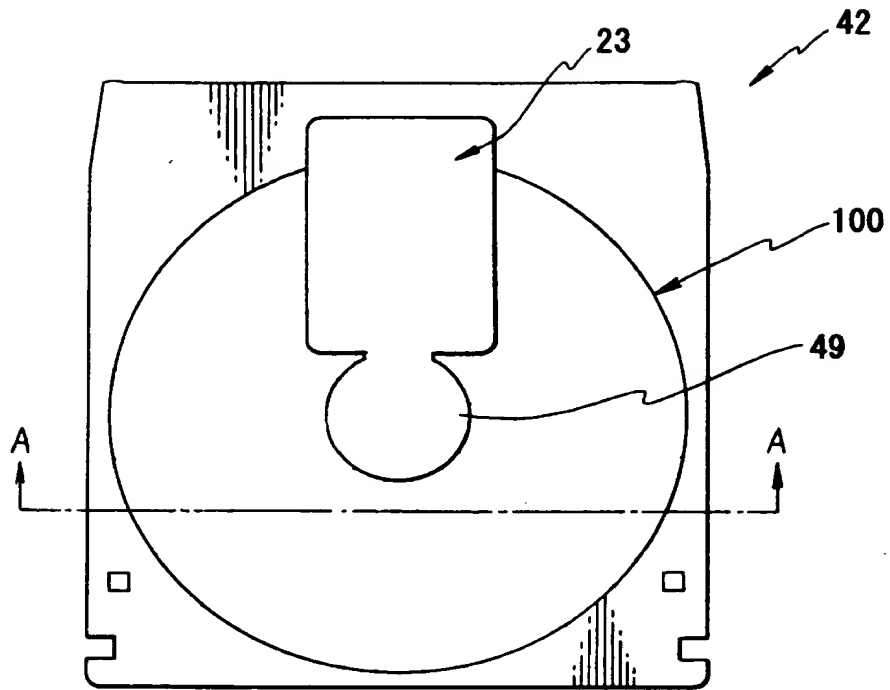


Fig. 14B

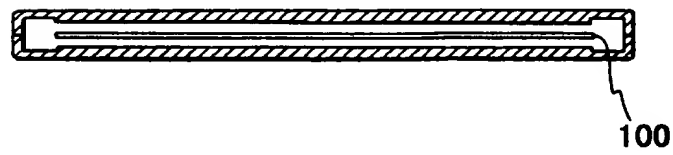


Fig. 15A

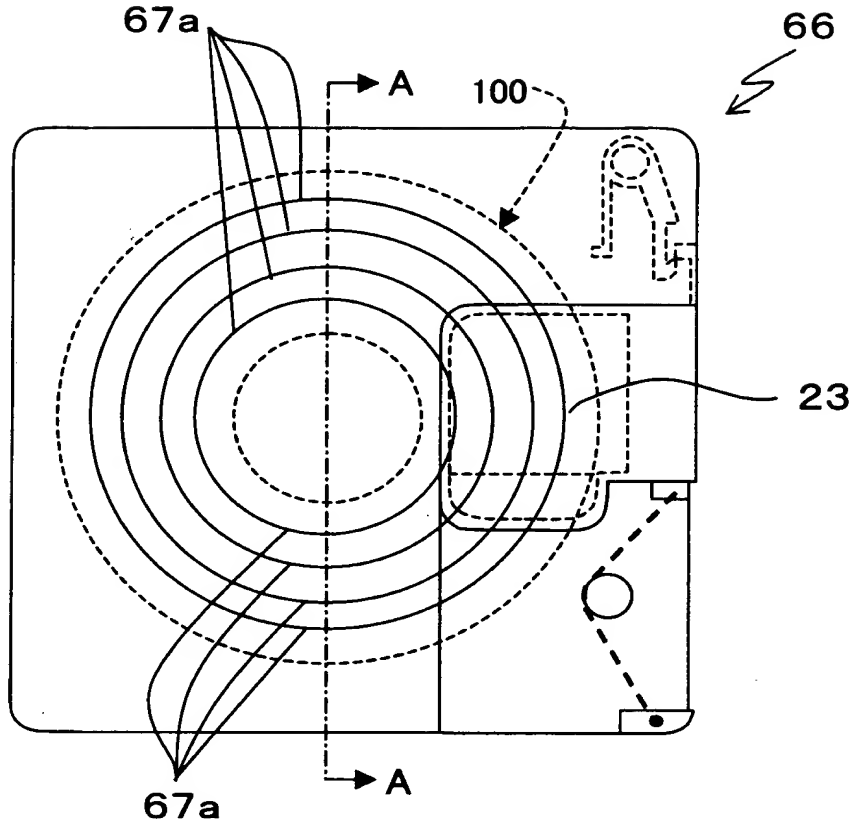


Fig. 15B

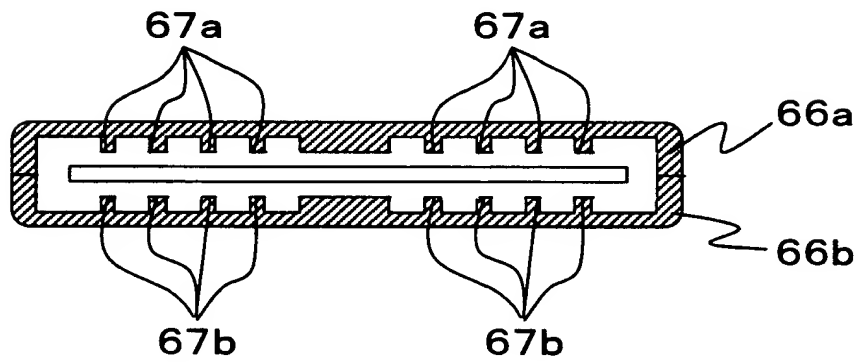


Fig. 16

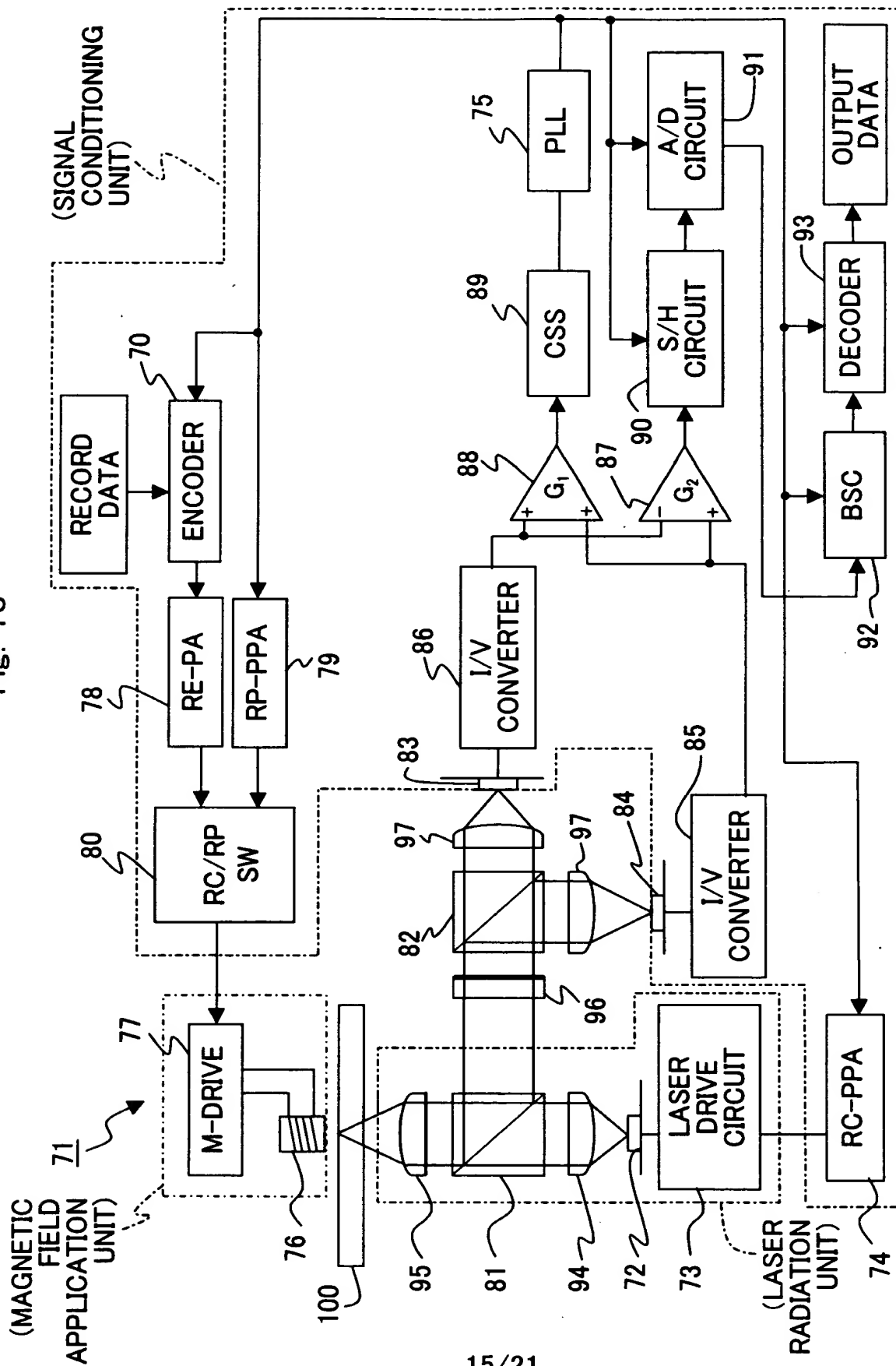






Fig. 18

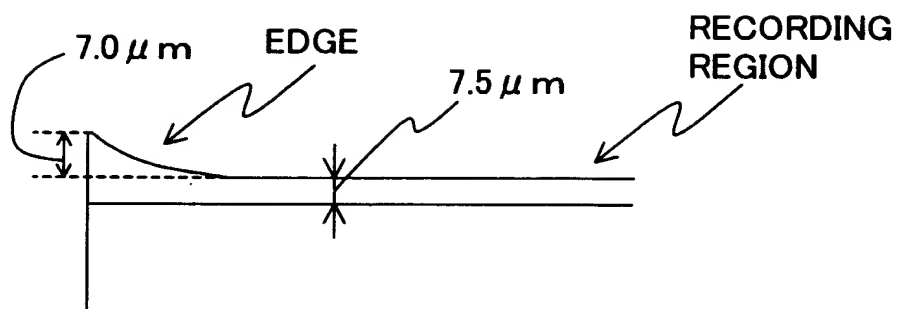


Fig. 13

Fig. 20

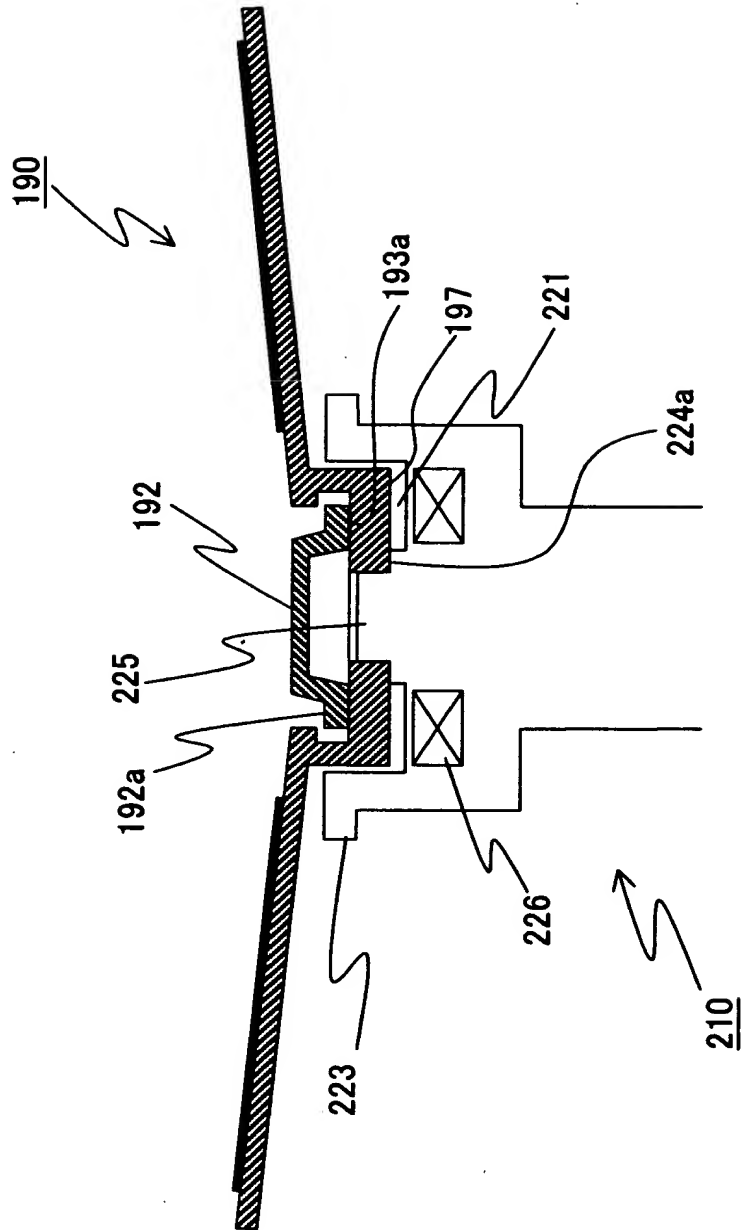


Fig. 21

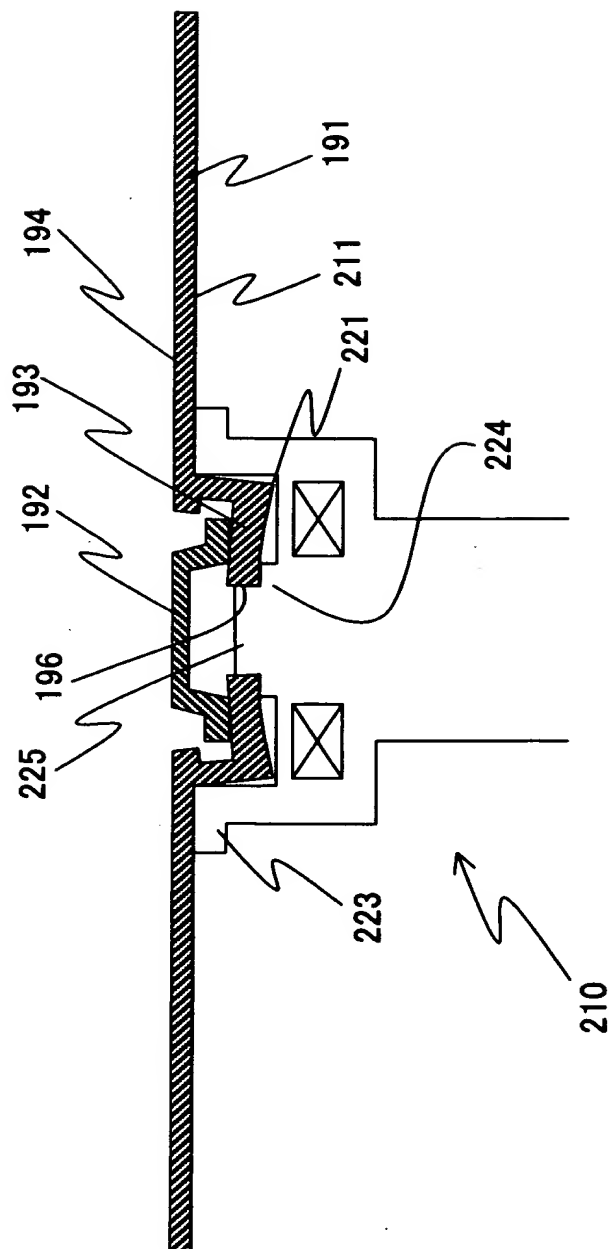


Fig. 22

